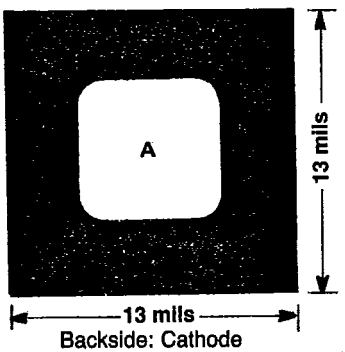
DIE NO. 1C914
LINE SOURCE — DSD241

Designed for general-purpose, high-speed switching applications.

This die provides performance equal to or better than that of the following device types:

1N914,A,B
1N3600
MMD6050
MMD7000
MSD7000*

*No longer available



Backside: Cathode

METALLIZATION —
Top ..... Al
Back ..... Au
BACKSIDE GOLD 3000Å
DIE THICKNESS ..... 6 ± 2 mils
BONDING PAD SIZE —
Anode ..... 6.0 x 6.0 mils

ELECTRICAL CHARACTERISTICS (T_A = 25°C; Note 1)

Parameter	Test Conditions	Min	Max	Unit
$V_{(BR)}$	$I_{(BR)}$ = 100 μAdc	100	—	Vdc
I_{R1}	V_R = 75 Vdc	—	5.0	μAdc
I_{R2}	V_R = 20 Vdc	—	25	mAdc
V_F	I_F = 10 mAdc	—	1.0	Vdc
C	V_R = 0	—	4.0	pF

NOTES:
1. Because of the limitations of probe testing, only dc parameters are tested. These parameters must be measured using pulse techniques: pulse width ≤ 300 μs, duty cycle ≤ 2%.
2. Detailed device characteristics are available from your Motorola sales representative.